Higher reliability in a smaller package

3D Silicon Capacitors

High stability and reliability capacitors
Low profile capacitors - 100 μm thick
High/extreme temperature capacitors - up to 250°C

Wire-bondable vertical capacitors - including high/extreme temperature & low profile
Wire-bondable embedded capacitors - including high/extreme temperature & low profile

Ultra broadband surface mounted & embedded capacitors - up to 100 GHz+
Ultra large-band wire-bondable vertical capacitors > 26 GHz
Ultra broadband surface mounted differential capacitor pair

Automotive high temperature capacitors - up to 200°C
Medical grade capacitors
Ultra low ESL and ultra low profile capacitors - 85 μm thick
Murata silicon capacitors
Overview

The best choice for all demanding applications

Murata high-density silicon capacitors have been developed with a semiconductor MOS process and are using the third dimension to substantially increase the capacitor surface and thus its capacitance without increasing the capacitor footprint. Murata silicon technology is based on a monolithic structure embedded in a monocristalline substrate (single MIM and multi MIM - Metal Insulator Metal).

Higher performance in a smaller package

This advanced 3D topology gives a developed area equivalent to 80 ceramic layers in an amazing 100 μm thickness (lower value on request) of active capacitance area. Thanks to a very linear and low dispersive dielectric, miniaturization, capacitance value and electrical performances are optimized.

Class-leading miniaturization

![Class 1 dielectric COG 10 x 10 nF 0603 400 μm thick = Murata SiCap 1x 100 nF 0402 100 μm thick](image)

10 times reliability of MLCCs

Coming from the same DNA as the semiconductor MOS process, Murata silicon capacitors have a default mode fully modeled with proven consistent data and offer therefore predictable and exceptional reliable performances. Our SiCap technology features high reliability – up to 10 times better than alternative capacitor technologies – mainly obtained thanks to the highly pure oxide generated during the high temperature curing. Furthermore, all electrical tests are completed at the end of the production steps which avoids early failures.

Murata Integrated Passive Solutions is located in Caen, France. The site includes an R&D center and a wafer foundry certified ISO 9001 / 14001, IATF 16949 for the automotive market as well as ISO 13485 for medical devices.
# Murata silicon capacitors meet the toughest requirements

Murata silicon capacitors are the best choice for all demanding applications in medical, automotive, communication, industrial and high-reliability markets such as downhole and aerospace.

<table>
<thead>
<tr>
<th>Model</th>
<th>Description</th>
<th>Operating Frequency</th>
<th>Max. temp.</th>
<th>Thickness</th>
<th>Assembly</th>
<th>Application</th>
</tr>
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<tbody>
<tr>
<td>HSSC</td>
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<td>X</td>
<td>X</td>
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<tr>
<td>LPSC</td>
<td>Low profile capacitor</td>
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<tr>
<td>HTSC</td>
<td>High temperature capacitor</td>
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<td>XTSC</td>
<td>Extreme temperature capacitor</td>
<td>125°C</td>
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<td>EXSC</td>
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<td>XBSC</td>
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<td>UBSC</td>
<td>Ultra broadband surface mounted capacitor</td>
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<tr>
<td>BBSC</td>
<td>Broadband surface mounted capacitor</td>
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<td>ULSC</td>
<td>Ultra large band surface mounted capacitor</td>
<td>1 GHz</td>
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<td>Ultra broadband surf. mounted differential cap. pair</td>
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<td>UBEC</td>
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<td>Broadband wire-bondable embedded capacitor</td>
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<td>WTSC</td>
<td>High temperature wire-bondable vertical capacitor</td>
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<td>WXSC</td>
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<td>2 kV</td>
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<td>WLSC</td>
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<tr>
<td>ATSC</td>
<td>Automotive high temperature capacitor</td>
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<td>UESL</td>
<td>Ultra low ESL and ultra low profile capacitor</td>
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<tr>
<td>MGSC</td>
<td>Medical grade capacitor</td>
<td></td>
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</tbody>
</table>

(*) Please refer to specification of each part number to get max operating frequency.
High stability & reliability Si capacitors (JEDEC/EIA compatible) (HSSC)

Murata High Stability Silicon Capacitors avoid the need to over-size the capacitor value for sensitive capacitive circuitry and offer a higher DC voltage stability. The IPD technology developed by Murata provides outstanding capacitor stability over the full operating voltage & temperature ranges. The very high and stable insulation resistance of silicon capacitors can improve battery lifetime up to 30% in mobile applications.

Key features
- Ultra high stability (temperature, voltage, aging).
- Low leakage current (high insulation resistance).
- Very low ESR and ESL.
- Negligible capacitance change with temperature variation.
- Low profile.

Finishing and packaging
- Lead-free NiAu finishing compatible with automatic soldering technologies (reflow and manual). Other terminations available on request.
- Tape and reel, waffle pack or wafer delivery.

Low profile Si capacitors down to 100 μm (LPSC)

The LPSC target antenna matching, RF filtering and decoupling of active dies, in applications with height and volume constraints. They offer low profile (100 μm thin, 80 μm on request), with very high stability upon applied voltage, very low leakage current and high level of performances. These capacitors are dedicated to Smart Card, RFID tags, medical... where integration plays a key role. The LPSC product family is splitted into two series:
- LPSC range from 47 pF to 1 μF, suitable for embedded technologies, modules, system in package, when designers are looking for utmost decoupling behaviour;
- LPSC ESD Enhanced range from 47 pF up to 330 pF that works efficiently and durably in RFID environments. Thanks to the full modeling of the elementary cell, the ESD capabilities have been optimized up to 8 kV (see Key Features below). Furthermore, our RFID Silicon capacitor range has been fine tuned in order to reach SRF up to 3 GHz, hence allowing unique fine tuning of the antenna, from 13.56 MHz up to UHF (800/900 MHz) applications.

Key features
- Ultra low profile (100 μm, 80 μm on request).
- High Q.
- Voltage stability.
- High ESD capabilities (ESD enhanced series):
  - >1 kV for 47 pF; >2 kV for 100 pF; >8 kV for 330 pF.
- Low leakage current down to 100 pA.
- Low ESR and low ESR.
- SRF = 1.2 GHz for 100 pF.

Finishing and packaging
- Lead-free NiAu finishing compatible with wirebonding or automatic soldering technologies. Aluminum pads on request.

Parameter | Value
---|---
Capacitance range | 47 pF to 3.3 μF(*)
Capacitance tolerances | ±15%(*)
Operating temperature range | -55°C to 150°C
Storage temperature range | -70°C to 165°C(**)
Temperature coefficient | +60 ppm/K
Breakdown Voltage (BV) | 11 VDC or 30 VDC
Capacitance variation versus RVDC | 0.1%/V (from 0 to RVDC)
Insulation resistance | 100 GΩ @ 3 V @ 25°C, t=120s, for 100nF
Aging | Negligible, < 0.001% / 1000h
Reliability | FIT=0.017 parts / billions hours
Capacitor thickness | 400 μm

(*) Other values on request  (**) w/o packing
Xtreme temperature Si capacitors up to 250°C (JEDEC/EIA compatible) (HTSC, XTSC)

Murata offers two JEDEC compatible capacitor ranges targeting applications in extreme conditions, like Hi Rel applications, the high temperature capacitors HTSC up to 200°C and the xtreme temperature capacitors XTSC up to 250°C. As an example of outstanding performance, the XTSC offer a 1 μF in 1206 with a temperature coefficient of +60 ppm/K over the full -55 °C/+250°C temperature range. Aging, stability of insulation resistance and capacitor value have been optimized to obtain the best product for Hi-Rel applications.

Key features
- Extended operating temperature range (up to 250°C) with low capacitance variation.
- High stability.
- High reliability.
- Low leakage current.
- Very low ESR and ESL.

Finishing and packaging
- Lead-free NiAu finishing compatible with wirebonding or leadframe soldering. Aluminum pads on request.
- Tape & reel, wafer pack or wafer delivery.

Wire-bondable or embedded low profile Si capacitors down to 100 μm (EMSC)

Murata Embedded Silicon Capacitors are designed to be compliant with the embedding process for printed circuit board and laminates. The EMSC can also be used with wire bond technologies. Thanks to the high robustness and performances of these silicon passive components, embedded processes are now reliable. The EMSC are available with a thickness of 100 μm (80 μm on request) and are the most appropriate solution for Chip On Board, Chip On Foil, Chip On Glass, Chip On Ceramic, flip chip and embedded applications.

Key features
- Ultra Low profile 100 μm (80 μm on request).
- High stability (temperature, voltage and aging).
- Low ESL and ESR.
- Low leakage current.
- High reliability.

Finishing and packaging
- Pad finishing in Aluminum. Other finishing available such as copper, nickel or gold. Applicable for almost all embedded applications.
- Tape & reel, wafer pack or wafer delivery.

(*): Other values on request
(**): 80 μm thickness on request
(***): 80 μm thickness on request

(Δ): Available parts. For other values, contact your Murata sales representative.
Extreme temp. wire-bondable Si capacitors up to 250°C (ETSC, EXSC)

The ETSC and EXSC series are designed to be compliant with high temperature wire bond technologies with Aluminum pads for Aluminum wedge bonding and gold pads on request for gold wire bonding. These capacitors feature low profile (250 μm), low leakage current and high operating temperature (ETSC up to 200°C/ EXSC up to 250°C) with high stability with temperature, voltage and negligible capacitance loss through aging. Applications include downhole industries, decoupling, filtering, charge pump, replacement of X8R and CDG dielectrics, and high reliability applications, mainly for Multi-Chip Module assemblies.

### Key features
- Ultra High operating temperature
  - ETSC: up to 200°C
  - EXSC: up to 250°C
- Low profile (250 μm)
- High stability (temperature, voltage and aging)
- Low leakage current
- High reliability

### Finishing and packaging
- Pad finishing in Aluminum. Other finishing available such as copper, nickel or gold.
- Tape & reel, waffle pack or wafer delivery.

### Ultra broadband surface mounted Si capacitors up to 100 GHz+
(XBSC 100 GHz+, UBSC 60 GHz+, BBSC 40 GHz, ULSC 20 GHz)

The XBSC/UBSC/BBSC/ULSC capacitors target optical communication systems (ROSA/TOSA, SONET and all optoelectronics) as well as high speed data systems. These ultra broadband capacitors are optimized for DC blocking, feedback, coupling and bypass applications in ultra broadband applications. They offer low insertion loss, low reflection and unique phase matching in transmission mode. They provide very high capacitance stability over temperature, voltage and aging.

### Key features
- Ultra broadband performance up to 110 GHz.
- Resonance free allowing ultra low group delay variation.
- Ultra low insertion loss thanks to an excellent impedance matching in transmission mode.
- Low ESL and low ESR in bypass grounding mode.
- High stability of capacitance value over temperature, voltage and aging.
- High reliability.

### Finishing and packaging
- Lead-free nickel/solder coating compatible with automatic soldering technologies: reflow and manual. Other top finishings available on request (ex: lead-free bumping - SAC305 type).
- Tape & reel, waffle pack, film frame carrier or raw wafer delivery.

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(*) Other values on request
(1) Ultra high performance, -55°C to 200°C
(2) 0402 - 47nF is under development for BBSC and ULSC.
(3) 0603 - 100nf - BV 11V available as ULSC only.

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Silicon capacitors
Ultra Broadband surface mounted differential Si capacitor pairs (UBDC 60 GHz+)

Ultra broadband smart products have been developed to keep pace with evolving optical communication market requirements and customers’ feedbacks. With an on-going miniaturization and improved performances of optoelectronics circuitycles, Murata offers some smart solutions by integrating differential capacitor pairs, matched termination...into a single silicon passive device. This unique integration based on ultra deep trench MOS Silicon offers unique performances with low insertion loss, low reflection and phase stability up to 67 GHz. These capacitors are fully compatible with high speed automated pick-and-place manufacturing operations and are available with ENIG termination and with SAC305 pre-bump for 0402M case size.

**Key features**
- Ultra broadband performance up to 67 GHz.
- Resonance free allowing ultra low group delay variation.
- Ultra low insertion loss thanks to an excellent impedance matching in transmission mode for UBB differential capacitor pair.
- Low ESL and low ESR in bypass grounding mode for UBB matched termination.
- High stability of capacitance value over temperature, voltage and aging. High reliability.
- Straight forward assembly process.

**Finishing and packaging**
- Lead-free nickel/solder coating compatible with automatic soldering technologies (reflow and manual).
- Tape and reel, film frame carrier or raw wafer delivery.

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Ultra broadband wire-bondable embedded Si capacitors up to 60 GHz+ (UBEC 60 GHz+, BBEC 40 GHz, ULEC 20 GHz)

The UBEC/BBEC/ULEC capacitors target optical communication systems (ROSA/TOSA, SONET and all optoelectronics) as well as high speed data systems or products. The UBEC/BBEC/ULEC are optimized for DC decoupling and bypass applications. They offer high rejection up to 60 GHz+ for the UBEC, up to 40 GHz for the BBEC and up to 20 GHz for the ULEC. The UBEC/BBEC/ULEC capacitors also provide very high capacitance stability over temperature (+60 ppm/K) and voltage.

**Key features**
- Ultra broadband performance up to 67 GHz.
- Resonance free allowing ultra low group delay variation.
- Ultra low insertion loss thanks to an excellent impedance matching in transmission mode.
- Low ESL and low ESR in bypass grounding mode.
- High stability of capacitance value over temperature, voltage and aging.
- High reliability.

**Finishing and packaging**
- Can be directly mounted on the PCB using die bonding and wire bonding(s). Capacitors with top electrodes in Aluminum. Other top finishings available on request (eg: Gold – TiWAu). Compatible with standard wire bonding assembly (ball and wedge) and embedding.
- Tape & reel (except for 0201M and 01005M), waffle pack, film frame carrier or raw wafer delivery.
The UWSC capacitors target **optical communication systems** (ROS/TOsA, SONET and all optoelectronic) as well as **high speed data systems** or products. The UWSC are optimized for DC decoupling and bypass applications. They offer high rejection at > 26 GHz. The UWSC capacitors also provide very high capacitance stability over temperature (+60 ppm/K) and voltage. These capacitors are compatible with standard wire bonding assembly (ball and wedge). The bottom electrode is in Ti/Ni/Au and the top electrode is in Gold (TiWAu).

### Key features
- Ultra large band performance higher than 26 GHz.
- Resonance free and phase stability.
- Unique capacitance value of 1 nF in 0101.
- High stability of capacitance value over temperature, voltage and aging.
- High reliability.
- Ultra low ESR and ESL.

### Finishing and packaging
- Can be directly mounted on the PCB using die bonding and wire bonding(s). Bottom electrode in Ti/Ni/Au and top electrode in Gold (TiWAu). Other top finishings available on request (e.g. Aluminum). Compatible with standard wire bonding assembly (ball and wedge).
- Tape and reel (up to 0202 case size included), wafer pack, film frame carrier or raw wafer delivery.

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The Wire Bonding vertical Silicon Capacitors target **RF High Power applications for wireless communication, radar, lidar and data broadcasting systems**. They are suitable for DC decoupling, matching network, and harmonic / noise filtering functions. They offer ultra high stability of capacitance value with temperature, voltage, and aging. The Wire Bonding vertical range is available up to +150°C (WBSC), up to +200°C (WTSC) and up to +250°C (WXSC).

### Key features
- Low profile 250 μm.
- Low leakage current.
- High stability (temperature and voltage).
- Negligible capacitance loss through aging.

### Finishing and packaging
- Can be directly mounted on the PCB using die bonding and wire bonding(s). Bottom electrode is in Ti/Ni/Au and top electrode in Gold (TiWAu) for WBSC and in Aluminum for WTSC/WXSC. Other top finishings available on request.
- Tape & reel (up to 0202 case size included), wafer pack, film frame carrier or raw wafer delivery.

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<table>
<thead>
<tr>
<th>Parameter</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Capacitance range</td>
<td>47 pF to 22 nF(*)</td>
</tr>
<tr>
<td>Capacitance tolerances</td>
<td>± 15 %(*5)</td>
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<tr>
<td>Operating temperature range</td>
<td>-55 °C to 150 °C</td>
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<tr>
<td>Storage temperature range</td>
<td>- 70 °C to 165 °C(**)</td>
</tr>
<tr>
<td>Temperature coefficient</td>
<td>+60 ppm/K</td>
</tr>
<tr>
<td>Breakdown Voltage (BV)</td>
<td>11 V, 30 V, 50 V, 100 V, 150 V, 450 V(*)</td>
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<tr>
<td>Capacitance variation versus RVDC</td>
<td>0.02 %/V (from 0 V to RVDC)</td>
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<td>Equivalent Series Inductance (ESL)</td>
<td>Typ. 6 pH @ SRF</td>
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<tr>
<td>Equivalent Series Resistance (ESR)</td>
<td>Typ. 14 mΩ(****)</td>
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<td>Insulation resistance</td>
<td>10GΩ @ RVDC @ 25°C t&gt;120s for 10nF</td>
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<td>Aging</td>
<td>Negligible, &lt; 0.001% / 1000h</td>
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<tr>
<td>Reliability</td>
<td>FIT&lt;0.017 parts / billions hours</td>
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<tr>
<td>Capacitor thickness</td>
<td>250 μm or 100 μm (*1)</td>
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(*) Other values on request  (**w/o packing  
(****) e.g. 10 nF/0303/BV 50V

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<td>Capacitance tolerances</td>
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<td>Operating temperature range</td>
<td>-55 °C to 250°C for WXSC</td>
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<tr>
<td>Storage temperature range</td>
<td>-70°C to 265°C(**) for WXSC</td>
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<tr>
<td>Temperature coefficient</td>
<td>+60 ppm/K</td>
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<tr>
<td>Breakdown Voltage (BV)</td>
<td>11 V, 30 V, 50 V, 100 V, 150 V, 450 V(*)</td>
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<td>Capacitance variation versus RVDC</td>
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<td>Equivalent Series Inductance (ESL)</td>
<td>Typ. 50 pH @ SRF</td>
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<td>Equivalent Series Resistance (ESR)</td>
<td>Typ. 50 mΩ</td>
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<td>Insulation resistance</td>
<td>10GΩ @ RVDC @ 25°C t+120s for 10nF</td>
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<tr>
<td>Capacitor thickness</td>
<td>250 μm</td>
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Available parts: For other values, contact your Murata sales representative. Under development.
Wire-bondable vertical low-profile Si capacitors down to 100 μm (WLSC)

The WLSC low-profile capacitors target **RF High Power applications** with height and volume constraints and can address wireless communication, radar and data broadcasting systems. The WLSC are suitable for DC decoupling, matching network, and harmonic / noise filtering functions. The unique technology of integrated passive devices in silicon developed by Murata can solve most of the problems encountered in demanding applications. These Si capacitors in ultra-deep trenches have been developed with a semiconductor process which enables the integration of high capacitance density from 1.55 nF/mm² to 250 nF/mm² (with a breakdown voltage of respectively 450 V to 11 V).

### Key features
- Ultra low profile 100 μm.
- Low leakage current.
- High stability (temperature and voltage).
- Negligible capacitance loss through aging.

### Finishing and packaging
- Can be directly mounted on the PCB using die bonding and wire bonding(s). Bottom electrode in Ti/Ni/Au and top electrode in Gold (TiWAu). Other top finishings available on request (ex: Aluminum). Compatible with standard wire bonding assembly (ball and wedge).
- Tape & reel (up to 0202 case size included), wafer pack, film frame carrier or raw wafer delivery.

### Automotive high temperature Si capacitors up to 200°C (ATSC)

The ATSC capacitors target **Under-the-Hood** electronics and all sensors exposed to harsh conditions in the **automotive market** segment. These automotive grade capacitors are optimized for decoupling functions. They are manufactured in Murata IATF 16949 certified facility, under AEC-Q100 conditions up to 200ºC.

### Key features
- Qualified according to AEC-Q100.
- High stability of capacitance value over temperature, voltage and aging.
- 16 V operating voltage.
- Load dump.
- 8 kV HBM ESD.
- Suitable for high temperature leadframe mounting.

### Finishing and packaging
- Pad finishing in Aluminum. Applicable for high temperature wirebonding and other mountings. Other finishings available such as nickel or gold.
- Tape and reel, wafer pack or wafer delivery.

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* (*) Other values on request  (***) w/o packing  (**) value depends on products

*△* Available parts. For other values, contact your Murata sales representative.

Under development.
Ultra low ESL and ultra low profile Si capacitors down to 85 μm (UESL)

The Ultra-low ESL (UESL) silicon capacitors target power integrity and signal integrity for high-speed applications. With an ultra-low ESL (Equivalent Series Inductance) and an excellent behavior in high frequencies, the UESL capacitors are the perfect match for power supply decoupling and bypass of high-speed digital IC. The UESL capacitors feature ultra-low thickness (85 μm and below) which enables advanced assembly with strong height restrictions (processor package, BGA land-side, package embedded...). The unique technology of integrated passive devices in silicon developed by Murata provides high stability over DC voltage and temperature.

**Key features**
- Ultra-low profile of 85 μm.
- Very low ESR and ESL.
- High stability.
- Low leakage current.

**Finishing and packaging**
- Lead-free NiAu finishing compatible with automatic soldering technologies (reflow and manual). Other terminations available upon request.
- Tape & reel or wafer delivery.

Medical grade Si capacitors (MGSC)

The MGSC silicon capacitor range targets high reliability medical applications such as implantable devices (pacemaker, defibrillator...). These capacitors are optimized in terms of reliability to avoid any burning test and to ensure that the initial failure rate is drastically lower than other ceramic types.

The very low leakage current enables to improve the performances of battery based applications and increase their lifetime.

**Key features**
- High reliability.
- Extreme low profile.
- High stability of capacitor value over voltage, temperature and aging.
- Die to die stacking.

**Finishing and packaging**
- Aluminum pads suitable for wirebonding assembly.
- Copper finishing option for embedded technology.
- Tape & reel. Other types of packagings on request (film frame carrier, raw wafer...).
Products handling, storage and shelf life indications

It is preferable to repack the remaining capacitors quantities after any process step, in the same conditions as before the opening (ESD bag + N2). The assembly of capacitors has to be done one year maximum after the opening date.

Store the capacitors in a clean environment and in the manufacturer’s package, without a rapid thermal change in an indoor room and with a temperature between -10 to 40 degree C.

To avoid contamination and damage like scratches and cracks, our recommendations are:

1. Die must never be handled with bare hands
2. Avoid touching the active face
3. Do not store and transport die outside protective bags, boxes, sawn tape
4. Work only in ESD environments
5. Plastic tweezers or a soft vacuum tool are recommended to remove the silicon die from the packing.

Standard packing is tape & reel for die size larger than 0201 but silicon capacitors can be provided within waffle pack, gelpak or sawing frame. Please contact the Murata sales contact for drawing and references (mis@murata.com).

The capacitors can be delivered in the following packaging: tape & reel, waffle pack, film frame carrier and raw wafer. Please contact Murata for drawing and references (mis@murata.com).

Packaging shelf life

<table>
<thead>
<tr>
<th>Packaging</th>
<th>Recommendations</th>
</tr>
</thead>
<tbody>
<tr>
<td>Raw wafer</td>
<td>6 years /8°C to 45°C, &lt;30% RH or dried N2</td>
</tr>
<tr>
<td>Film frame carrier D175 Adwill</td>
<td>12 months 18-40°C / RH&lt;60% (or dried N2) in the dark (UV performed)</td>
</tr>
<tr>
<td>Film frame carrier D510 Adwill</td>
<td>12 months 23 ± 5°C / 40%-RH&lt;60% (or dried N2) in the dark (UV not performed)</td>
</tr>
<tr>
<td>Tape and reel</td>
<td>5 years 18-35°C / RH: 35-65% or dried N2</td>
</tr>
<tr>
<td>Waffle pack</td>
<td>5 years 18-35°C / RH: 35-65% or dried N2</td>
</tr>
<tr>
<td>Conductive bags</td>
<td>5 years</td>
</tr>
</tbody>
</table>
Assembly instructions

The attachment techniques recommended by Murata for silicon capacitors on the customer’s substrates are fully detailed in specific documents available on our website. To assure the correct use and proper functioning of Murata Silicon capacitors please download the assembly instructions on www.murata.com and read them carefully.

<table>
<thead>
<tr>
<th>Title of the assembly note available on our website</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>HSSC Capacitors 400 μm - Assembly by Soldering</td>
<td>High stability and reliability capacitor</td>
</tr>
<tr>
<td>LPSC Capacitors 100 μm - Assembly by Soldering</td>
<td>Low profile capacitor</td>
</tr>
<tr>
<td>HTSC Capacitors 400 μm - Assembly by Soldering</td>
<td>High temperature capacitor</td>
</tr>
<tr>
<td>XTSC Capacitors 400 μm - Assembly by Soldering</td>
<td>Extreme temperature capacitor</td>
</tr>
<tr>
<td>EMSC Capacitors - Assembly by Wirebonding</td>
<td>Wire-bondable &amp; embedded low profile capacitor</td>
</tr>
<tr>
<td>ETSC / EXSC Capacitors 250 μm - Assembly by Wirebonding</td>
<td>High temperature wire-bondable capacitor</td>
</tr>
<tr>
<td>XTSC / EXSC Capacitors 250 μm - Assembly by Wirebonding</td>
<td>Extreme temperature wire-bondable capacitor</td>
</tr>
<tr>
<td>UBSC / UBDC/ UBSC / BBSC / ULSC Capacitors 100 μm &amp; 400 μm - Assembly by Soldering</td>
<td>Extreme broadband surface mounted capacitor</td>
</tr>
<tr>
<td>UBEC / BBEC / ULEC Capacitors 100 μm &amp; 400 μm - Assembly by Wirebonding</td>
<td>Ultra broadband surface mounted capacitor</td>
</tr>
<tr>
<td>UBEC / BBEC / ULEC Capacitors 100 μm &amp; 400 μm - Assembly by Wirebonding</td>
<td>Broadband surface mounted capacitor</td>
</tr>
<tr>
<td>UBEC / BBEC / ULEC Capacitors 100 μm &amp; 400 μm - Assembly by Wirebonding</td>
<td>Ultra large band surface mounted capacitor</td>
</tr>
<tr>
<td>UBDC / BBDC / UBDSC / BBDC / UBDSC / UBDSC Capacitors 100 μm &amp; 400 μm - Assembly by Soldering</td>
<td>Ultra large band wire-bondable embedded capacitor</td>
</tr>
<tr>
<td>UESL Capacitors 85 μm - Assembly by Soldering</td>
<td>Wire-bondable &amp; embedded low profile capacitor</td>
</tr>
<tr>
<td>UESL Capacitors 85 μm - Assembly by Soldering</td>
<td>High temperature automotive capacitor</td>
</tr>
<tr>
<td>UESL Capacitors 85 μm - Assembly by Soldering</td>
<td>Ultra low ESL and ultra low profile capacitor</td>
</tr>
</tbody>
</table>
The 3D Murata technologies provide several passive components including High Density Capacitors. The lifetime of these 3D Silicon Capacitors has been determined using accelerated lifetime tests.

The Time-Dependent Dielectric Breakdown (TDBB) measurements are used to model the intrinsic behavior of the capacitor dielectric under elevated temperature and strong electric field. The acceleration factors for temperature and electric field are used to extrapolate the capacitor lifetime under typical operating conditions.

The Temperature Cycling (TMCL) tests are done to assess the endurance of non-hermetic packaged solid-state devices exposed to thermo-mechanical stress as a result of expansion and contraction by high and low temperature.

Lifetime of these capacitors depends on the applied voltage and operating temperature. Please refer to our application note ‘Lifetime of 3D capacitors in Murata technologies’ for more details.
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2. Aerospace equipment
3. Undersea equipment
4. Power plant equipment
5. Medical equipment
6. Transportation equipment (vehicles, trains, ships, etc.)
7. Traffic signal equipment
8. Disaster prevention / crime prevention equipment
9. Data processing equipment
10. Application of similar complexity and/or reliability requirements to the applications listed above

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Please read rating and CAUTION (for storage, operating, rating, soldering, mounting and handling) in this catalog to prevent smoking and/or burning, etc.

This catalog has only typical specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.

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